


## APPLICATION DATA SHEET

Electronic Version v14

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<b>Title of Invention</b>	[METHOD OF FABRICATING FLIP CHIP BALL GRID ARRAY PACKAGE]		
<b>Application Type :</b> regular, utility <b>Attorney Docket Number :</b> 11182-US-PA			
<b>Correspondence address:</b> <b>Customer Number:</b> 31561 			
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